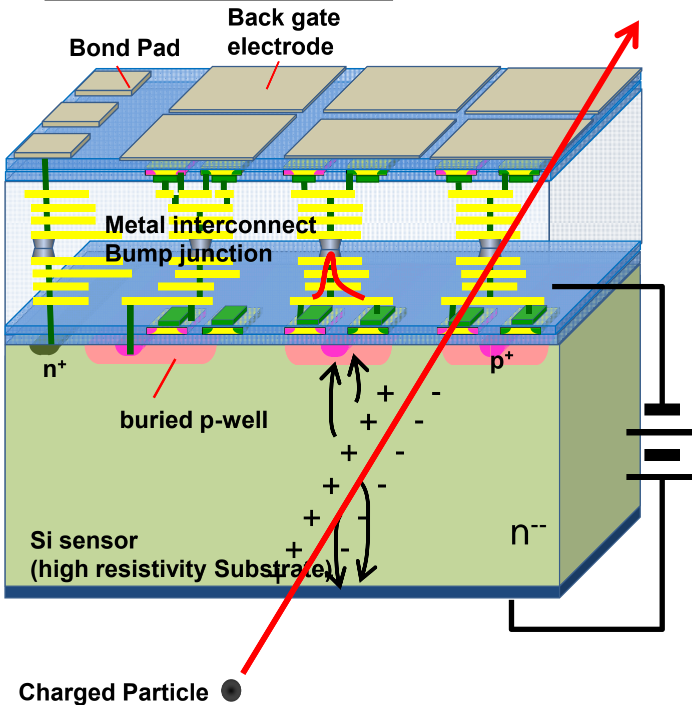
T-Micro

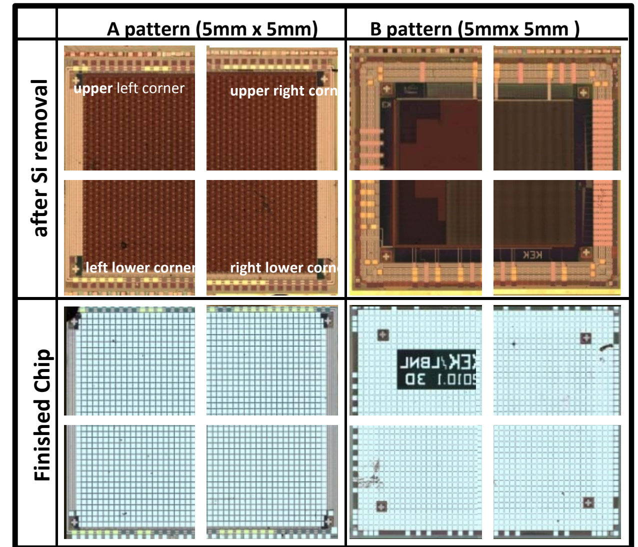
Stacked 3D-IC technology using μ-bumps

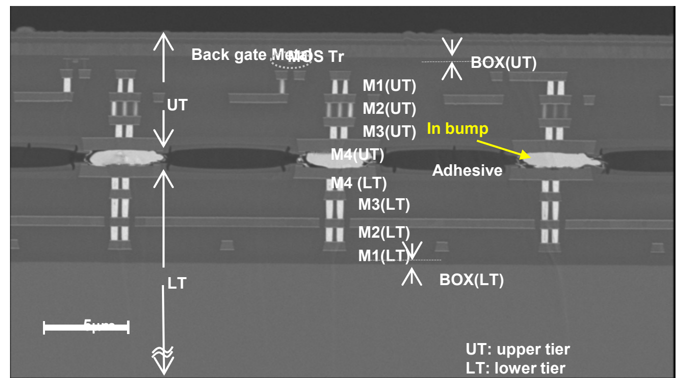
3D stacking technology with 2.5μm x 2.5μm Au (Gold) bump connections with adhesive injection. This technology is applicable image sensor and X-ray detector, IR detector and element particle detector with high frame rate and high resolution

Min. bump pitch	: 5 μm
Bump size	: 2.5 μm x 2.5 μm
Min. pad opening size	: 3.0 μm x 3.0 μm
Bump height	: 1.7 μm
Highest process Temperature	: 200℃

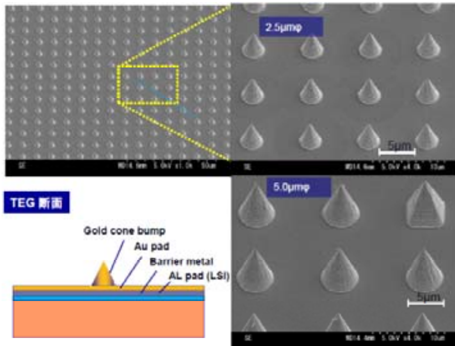
Demonstration chip

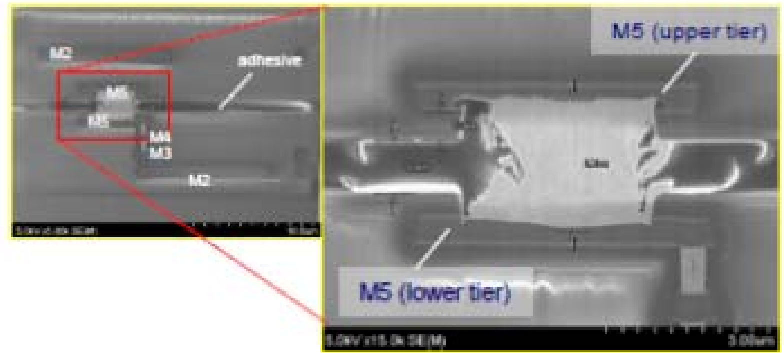






5μm pitch Au cone bump connection





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